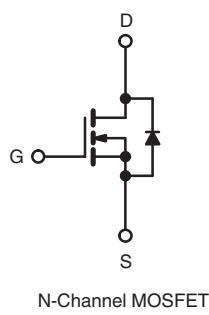
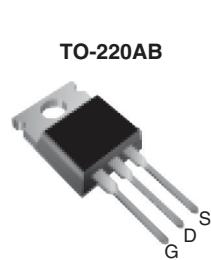


## Power MOSFET

PRODUCT SUMMARY		
$V_{DS}$ (V)	50	
$R_{DS(on)}$ ( $\Omega$ )	$V_{GS} = 10$ V	0.10
$Q_g$ (Max.) (nC)	17	
$Q_{gs}$ (nC)	9.0	
$Q_{gd}$ (nC)	3.0	
Configuration	Single	



### ORDERING INFORMATION

Package	TO-220AB
Lead (Pb)-free	IRFZ20PbF SiHFZ20-E3
SnPb	IRFZ20 SiHFZ20

### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage <sup>a</sup>	$V_{DS}$	50	V
Gate-Source Voltage <sup>a</sup>	$V_{GS}$	$\pm 20$	
Continuous Drain Current	$V_{GS}$ at 10 V	$I_D = 25$ °C 15	A
		$I_D = 100$ °C 10	
	$I_{DM}$	60	
Single Pulse Avalanche Energy <sup>c</sup>	$E_{AS}$	5	mJ
Linear Derating Factor (see fig. 16)		0.32	W/°C
Maximum Power Dissipation (see fig. 16)	$T_C = 25$ °C	$P_D$	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature)	for 10 s	300 (0.063" (1.6 mm) from case	

#### Notes

- a.  $T_J = 25$  °C to 150 °C
- b. Repetitive rating: Pulse width limited by max. junction temperature. See transient temperature impedance curve (see fig. 11).
- c. Starting  $T_J = 25$  °C,  $L = 0.07$  mH,  $R_g = 25$  Ω,  $I_{AS} = 12$  A

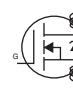
\* Pb containing terminations are not RoHS compliant, exemptions may apply


**RoHS\***  
COMPLIANT

**THERMAL RESISTANCE RATINGS**

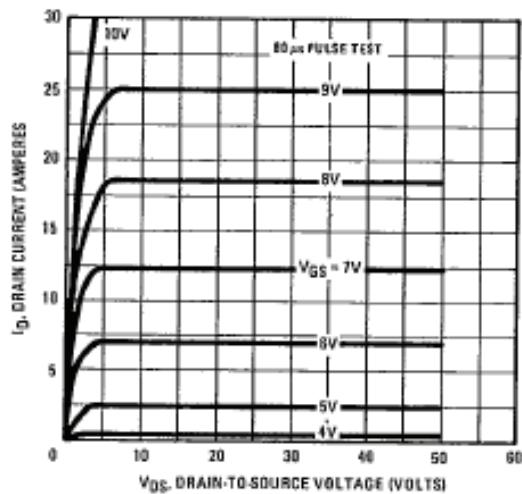
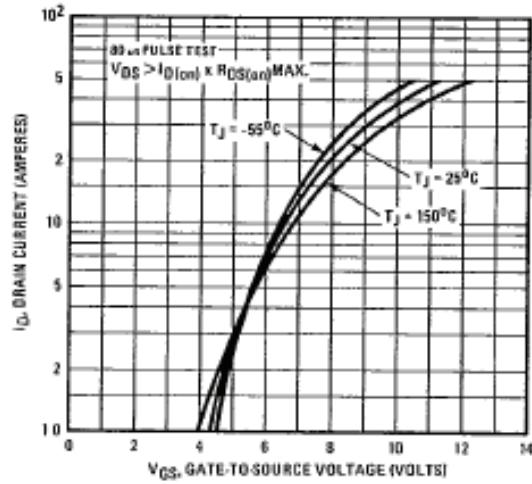
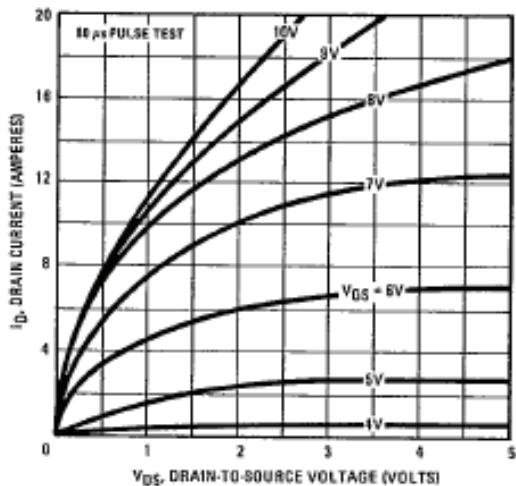
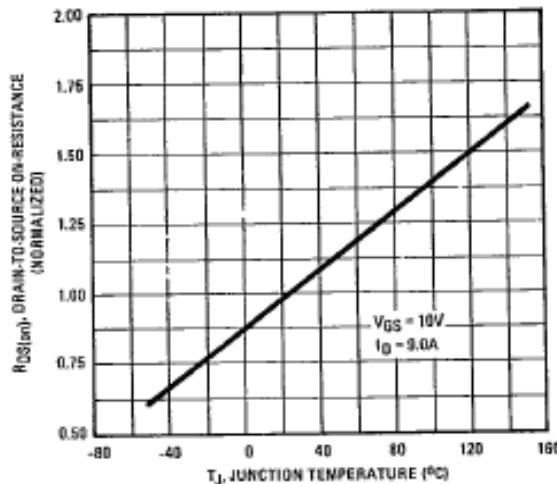
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Typical Socket Mount, Junction-to-Ambient	$R_{thJA}$	-	80	°C/W
Case-to-Sink, Mounting Surface Flat, Smooth, and Greased	$R_{thCS}$	1.0	-	
Junction-to-Case	$R_{thJC}$	-	3.12	

**ELECTRICAL CHARACTERISTICS** ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
<b>Static</b>							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}$ , $I_D = 250\text{ }\mu\text{A}$	50	-	-	V	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	2.0	-	4.0	V	
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20\text{ V}$	-	-	$\pm 500$	nA	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} > \text{Max. Rating}$ , $V_{GS} = 0\text{ V}$	-	-	250	$\mu\text{A}$	
		$V_{DS} = \text{Max. Rating} \times 0.8$ , $V_{GS} = 0\text{ V}$ , $T_C = 125^\circ\text{C}$	-	-	1000		
On-State Drain Current	$I_{D(on)}$	$V_{GS} = 10\text{ V}$	$V_{DS} > I_{D(on)} \times R_{DS(on)}$ max.	-	-	A	
Drain-Source On-State Resistance <sup>b</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 10\text{ A}$	-	0.080	0.10	
Forward Transconductance <sup>b</sup>	$g_{fs}$	$V_{DS} > I_{D(on)} \times R_{DS(on)}$ max., $I_D = 9.0\text{ A}$	5.0	6.0	-	S	
<b>Dynamic</b>							
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}$ , $V_{DS} = 25\text{ V}$ , $f = 1.0\text{ MHz}$ , see fig. 11	-	560	860	pF	
Output Capacitance	$C_{oss}$		-	250	350		
Reverse Transfer Capacitance	$C_{rss}$		-	60	100		
Total Gate Charge	$Q_g$	$V_{GS} = 10\text{ V}$	$I_D = 20\text{ A}$ , $V_{DS} = 0.8$ max. rating, see fig. 18 for test circuit (Gate charge is essentially independent of operating temperature)	-	12	17	nC
Gate-Source Charge	$Q_{gs}$			-	9.0	-	
Gate-Drain Charge	$Q_{gd}$			-	3.0	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 25\text{ V}$ , $I_D = 9.0\text{ A}$ , $Z_0 = 50\text{ }\Omega$ , see fig. 5 <sup>b</sup>	-	15	30	ns	
Rise Time	$t_r$		-	45	90		
Turn-Off Delay Time	$t_{d(off)}$		-	20	40		
Fall Time	$t_f$		-	15	30		
Internal Drain Inductance	$L_D$	Modified MOSFET symbol showing the internal device inductances		-	3.5	-	nH
Internal Source Inductance	$L_S$			-	4.5	-	
<b>Drain-Source Body Diode Characteristics</b>							
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p - n junction rectifier		-	-	15	A
Pulsed Diode Forward Current <sup>a</sup>	$I_{SM}$			-	-	60	
Body Diode Voltage <sup>b</sup>	$V_{SD}$	$T_C = 25^\circ\text{C}$ , $I_S = 15\text{ A}$ , $V_{GS} = 0\text{ V}$	-	-	1.5	V	
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J = 150^\circ\text{C}$ , $I_F = 15\text{ A}$ , $dI_F/dt = 100\text{ A}/\mu\text{s}$	-	100	-	ns	
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	0.4	-	$\mu\text{C}$	
Forward Turn-On Time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )					

**Notes**

a. Repetitive rating: Pulse width limited by max. junction temperature. See transient temperature impedance curve (see fig. 5).  
b. Pulse test: Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Fig. 1 - Typical Output Characteristics**

**Fig. 3 - Typical Transfer Characteristics**

**Fig. 2 - Typical Saturation Characteristics**

**Fig. 4 - Normalized On-Resistance vs. Temperature**

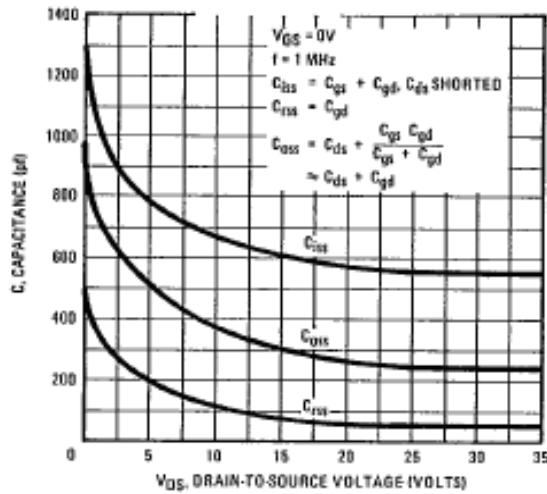


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

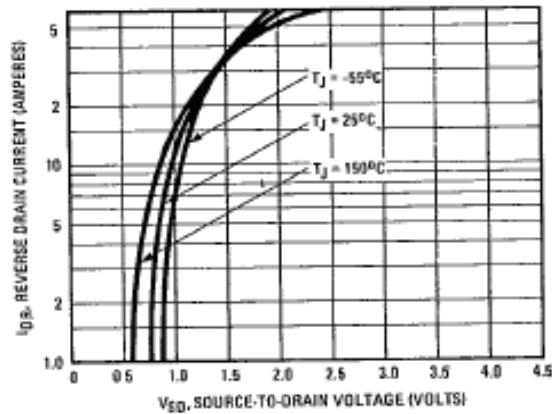


Fig. 7 - Typical Source-Drain Diode Forward Voltage

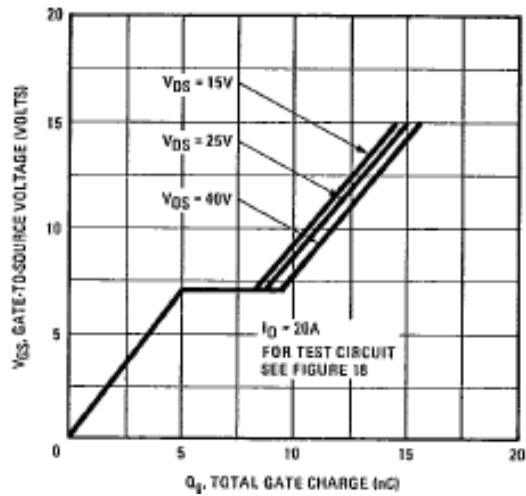


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

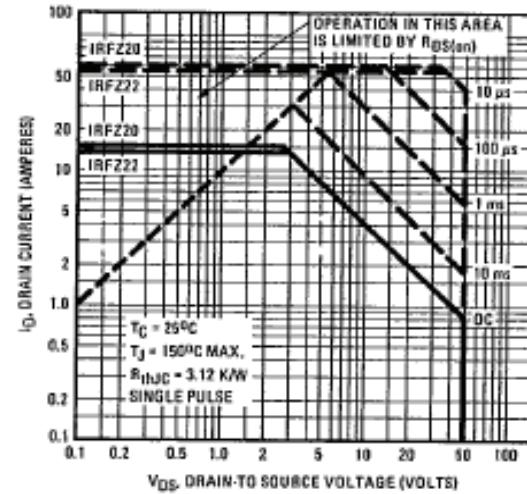


Fig. 8 - Maximum Safe Operating Area

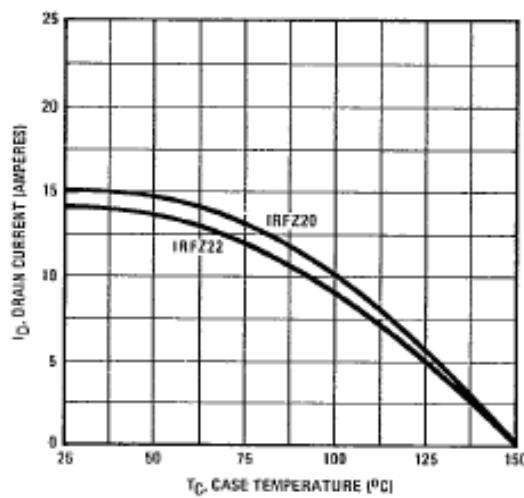


Fig. 9 - Maximum Drain Current vs. Case Temperature

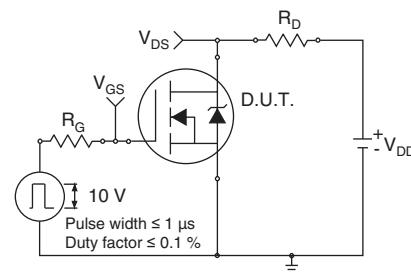


Fig. 10a - Switching Time Test Circuit

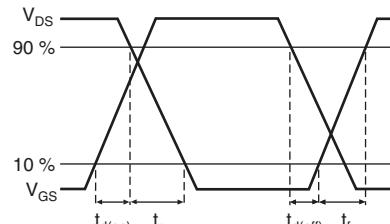


Fig. 10b - Switching Time Waveforms

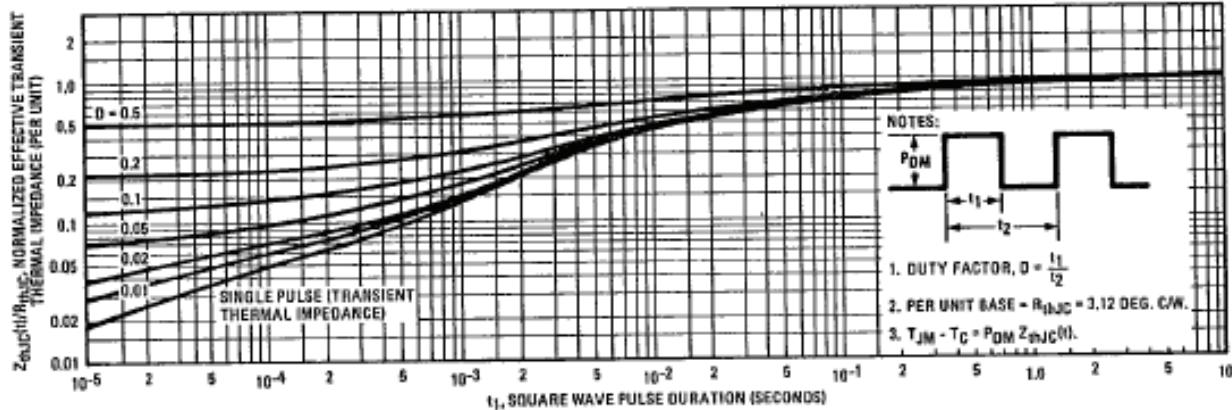


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case vs. Pulse Duration

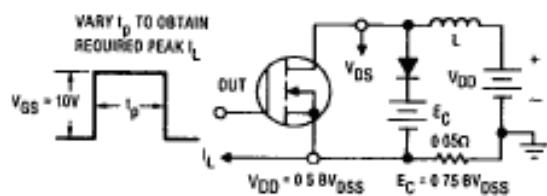


Fig. 12a - Clamped Inductive Test Circuit

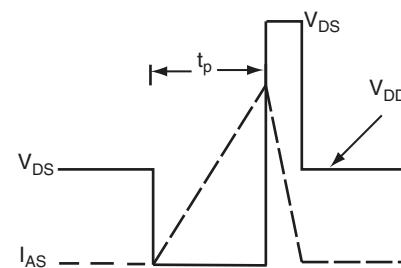


Fig. 12b - Unclamped Inductive Waveforms

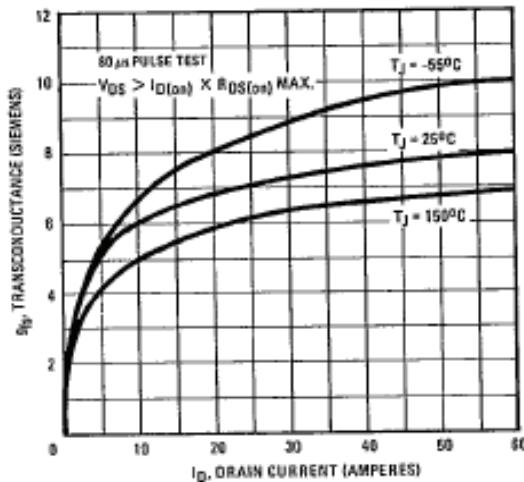


Fig. 13 - Typical Transconductance vs. Drain Current

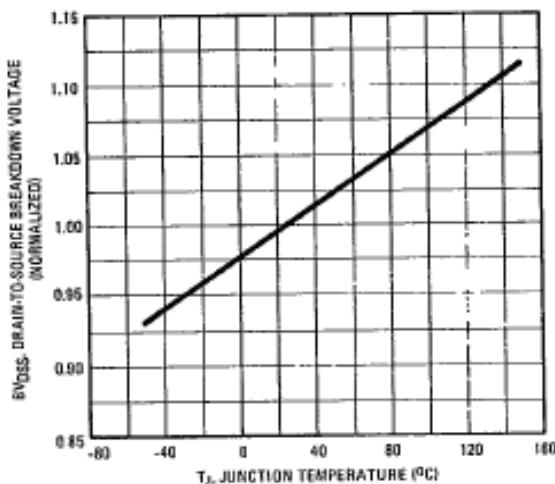


Fig. 14 - Breakdown Voltage vs. Temperature

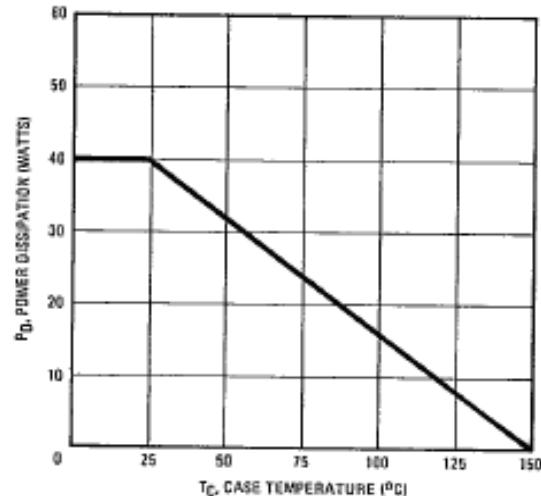


Fig. 16 - Power vs. Temperature Derating Curve

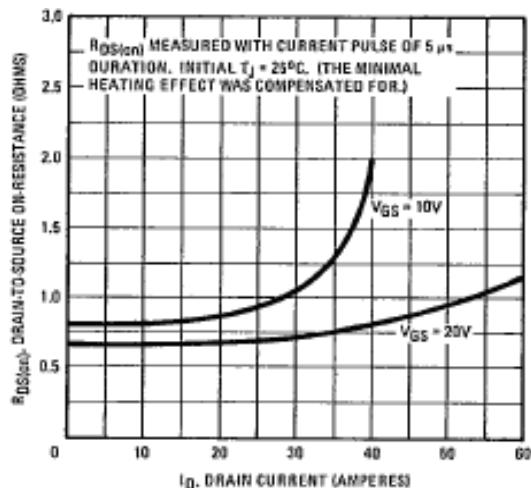


Fig. 15 - Typical On-Resistance vs. Drain Current

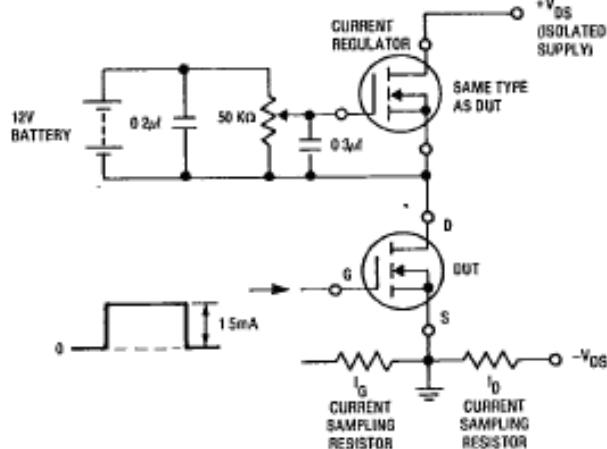
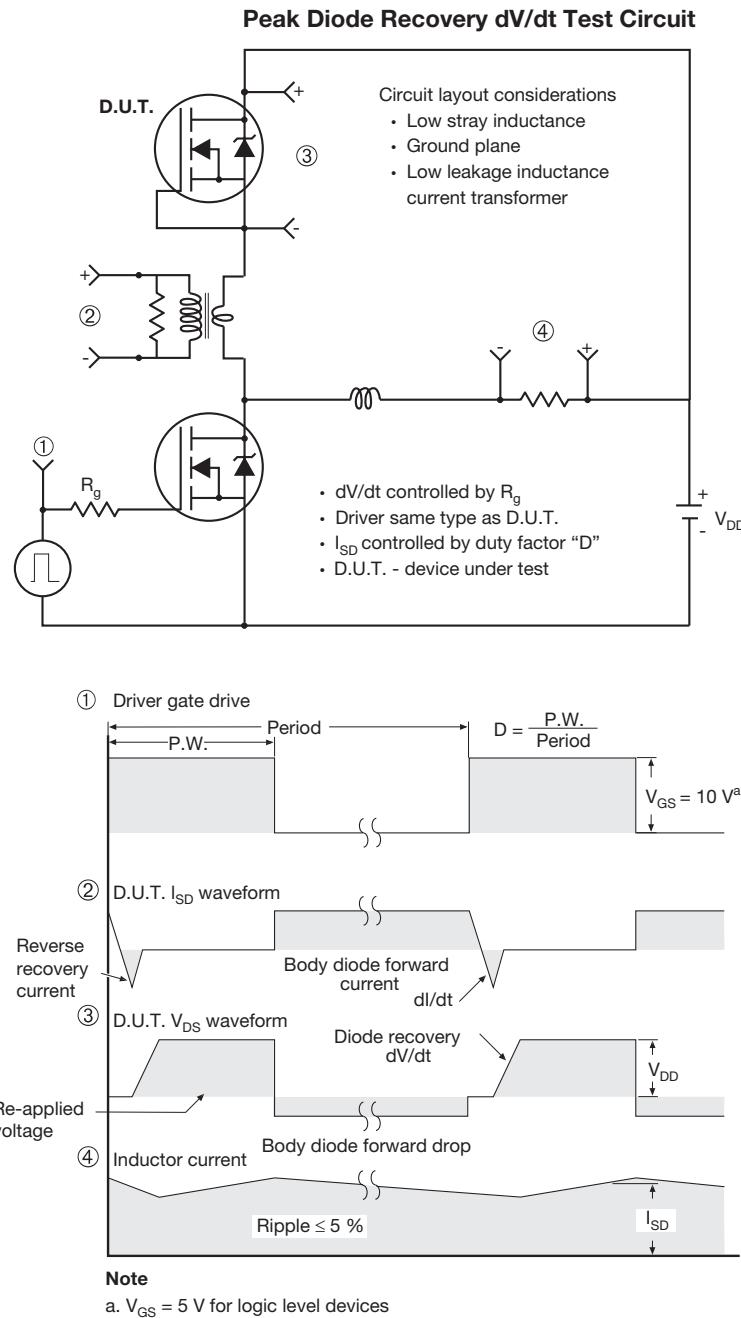


Fig. 17 - Gate Charge Test Circuit


**Fig. 14 - For N-Channel**

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